



厦门华联电子股份有限公司

Xiamen Hualian Electronics Corp., Ltd.

产品规格书

SPECIFICATION

产品名称：光 MOS 固态继电器

DESCRIPTION: Photo MOSFET Solid State Relay

产品型号：HSSR-16S1A0D-2

PART NO.: HSSR-16S1A0D-2

拟制 Prepared	审核 Verified	批准 Approved

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1 概述 General

产品 HSSR-16S1A0D-2 由砷化铝镓红外发光二极管作为输入级耦合到高压输出光探测电路。光探测电路由高速光电二极管阵列和驱动电路构成，用以开启/关断两个独立的高压金属氧化物半导体场效应管 (MOSFET)。一个最小 5mA 的电流流经输入级红外发光二极管可确保继电器动作。当加在输入级红外发光二极管的正向压降为 0.8V 或更小值时，继电器可确保复位。产品见图 1。



图 1 产品 Figure 1-Product

The HSSR-16S1A0D-2 consists of a AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit. The detector consists of a high-speed photovoltaic diode array and driver circuitry to switch on/off two discrete high voltage MOSFETs. The relay action with a minimum input current of 5mA through the input LED. The relay reset with an input voltage of 0.8V or less. Products shown in Figure 1.

2 特点 Features

- 单通道常开型单刀单掷继电器。Single Channel Normally on Single-Pole-Single-Throw (SPST) Relay.
- SOP16L 塑料封装 (SOP16L Plastic Package)
- 1500V 输出耐压产品。1500V Output Withstand Voltage.
- 低输入电流，CMOS 兼容。Low Input Current: CMOS Compatibility.
- 非常高的断开阻抗：典型值 10 兆欧。

Very High Output Off -state Impedance: 10 Teraohms Typical.

- 爬电距离 Clearances $\geq 8\text{mm}$.
- 非常快的开关速度 High Speed Switching: $T_{\text{ON}} < 4\text{ms}$, $T_{\text{OFF}} < 0.5\text{ms}$.
- 高输入输出绝缘耐压：5000Vrms for 1 min。

High Input-to-Output Insulation Voltage: 5000 Vrms for 1 min.

3 应用 Applications

- 电信切换。Telecommunication Switching.
- 数据通讯。Data Communications.
- 电池管理。Battery management.
- 工业控制。Industrial Controls.
- 医疗设备。Medical equipment.
- EMR/机械继电器替代。EMR / Reed Relay Replacement.

4 电原理图与及布线方式 Circuit Diagram and Wiring Diagram

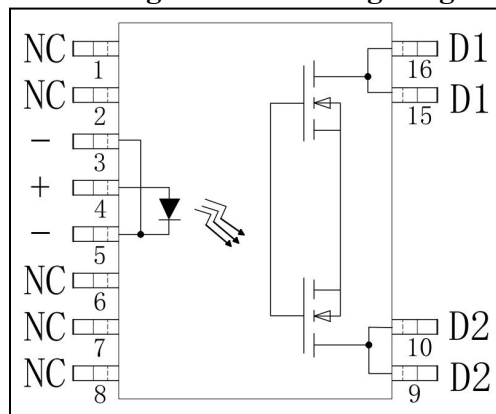


图 2 电原理图 Figure 2-Schematic

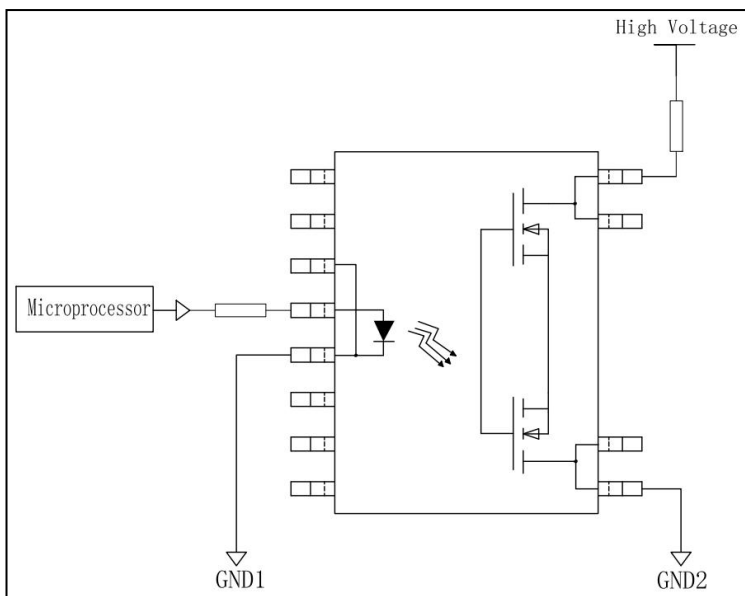


图 3 典型布线图 Figure 3-Typical wiring diagram

5 极限参数 Absolute Maximum Ratings

表 1 极限参数

Table 1-Absolute Maximum Ratings

参数名称 Characteristic		符号 Symbol	额定值 Rating	单位 Unit
输入端 Input	正向电流 Forward Current	I_F	60	mA
	反向电压 Reverse Voltage	V_R	6	V
	正向脉冲电流 Pulse Forward Current ($<1\mu s$ pulse width, 300 pps)	I_{FP}	1	A
	耗散功率 Power Dissipation (Single channel)	P_M	100	mW
输出端 output	开关电压 Switching Voltage	$V_{O(MAX)}$	1500	V
	连续通态电流 Continuous load current	$I_{O(MAX)}$	20	mA
	耗散功率 Power dissipation	P_C	1000	mW
工作温度 Operating temp.		T_{aop}	-40 ~ +125	°C
贮存温度 Storage temp.		T_{stg}	-55 ~ +125	°C
焊接温度 Soldering Temperature	手工焊 Hand Soldering (3 Sec.)	T_{sld}	360	°C
	回流焊 Reflow Soldering (10Sec.)		260	
绝缘电压 Isolation voltage (RH≤60%,交流 1 分钟) (RH≤60%, AC 1min.)		V_{ISO}	5000	V_{rms}

6 推荐工作条件 Recommended Operating Conditions

表 2 推荐工作条件

Table 2-Recommended Operating Conditions

参数名称 Characteristic	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit.
输入端电流 Input Current (ON)	$I_{F(ON)}$	7	30	mA
输入端电压 Input Voltage (OFF)	$V_{F(OFF)}$	-5	0.4	V
连续负载电流 Continuous Load Voltage (DC)	V_O	0	1000	V_{DC}
负载电流 Load Current	I_O	-10	10	mA
工作温度 Operating temp.	T_{aop}	-40	+125	°C

7 光电参数 Opto-Electrical Characteristics

表 3 光电参数

Table 3-Opto-Electrical Characteristics

$T_a=25^{\circ}C$

参数名称 Characteristic	符号 Symbol	测试条件 Test conditions	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit	
输入端 Input	正向电压 Forward voltage	V_F	$I_F=10mA$	1.1	1.35	1.5	V
	反向电流 Reverse current	I_R	$V_R=5V$	-	-	10	uA
	反向击穿电压 Reverse Breakdown Voltage	BV_R	$I_R=10\mu A$	5			V
	输入端子电容 Input Capacitance	C_{IN}	$V=0V$ $F=1MHz$		30		pF
	动作电流 Action Current	$I_{F(ON)}^a$	$I_O=10mA$			5	mA
输出端 Output	输出端耐压 Output Withstand Voltage	$V_{O(OFF)}$	$I_O=250uA$	1500			V
	断态漏电流 OFF-State Leakage Current	$I_{O(OFF)}$	$V_O=1500V$			10	uA
	导通电阻 ON Resistance	R_{ON}	$I_O=10mA, I_F=5mA$		180	300	Ω
传输 Xfer	动作时间 Action Time	T_{ON}^b	$I_F=10mA, I_O=20mA$			4.0	ms
	复位时间 Reset Time	T_{OFF}^b	$I_F=10mA, I_O=20mA$			0.5	ms
隔离 Isolation	耦合电容 Coupled Capacitance	$C_{I/O}$	$f_o = 1MHz$		0.6		pF
	绝缘电阻 Isolation Resistance	R_{I-O}	$V_{I-O} = 1000V, DC$	10^9			Ω
	绝缘电压 Isolation voltage	V_{ISO}	$I_{off} \leq 0.3mA,$ AC, 60s	5000			V

^a 保证所有器件在 I_F 值小于或等于最大的 $I_{F(ON)}$ 时动作。

It is guaranteed that all devices active when I_F value is less than or equal to the maximum value of $I_{F(ON)}$.

^b T_{ON} 与 T_{OFF} 测试电路见图 4。 Figure 4. is the test circuit of T_{ON} and T_{OFF} 。

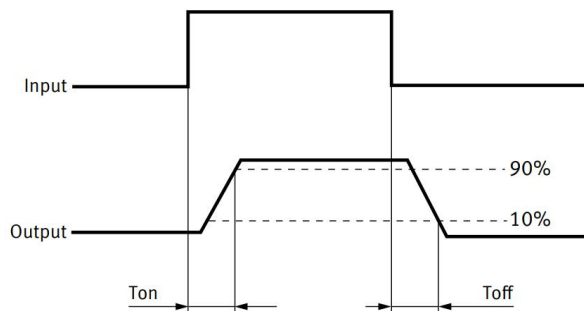


图 4 T_{ON} 与 T_{OFF} 测试方法 Figure 4- The test method of T_{ON} and T_{OFF}

8 外形尺寸 Dimensions

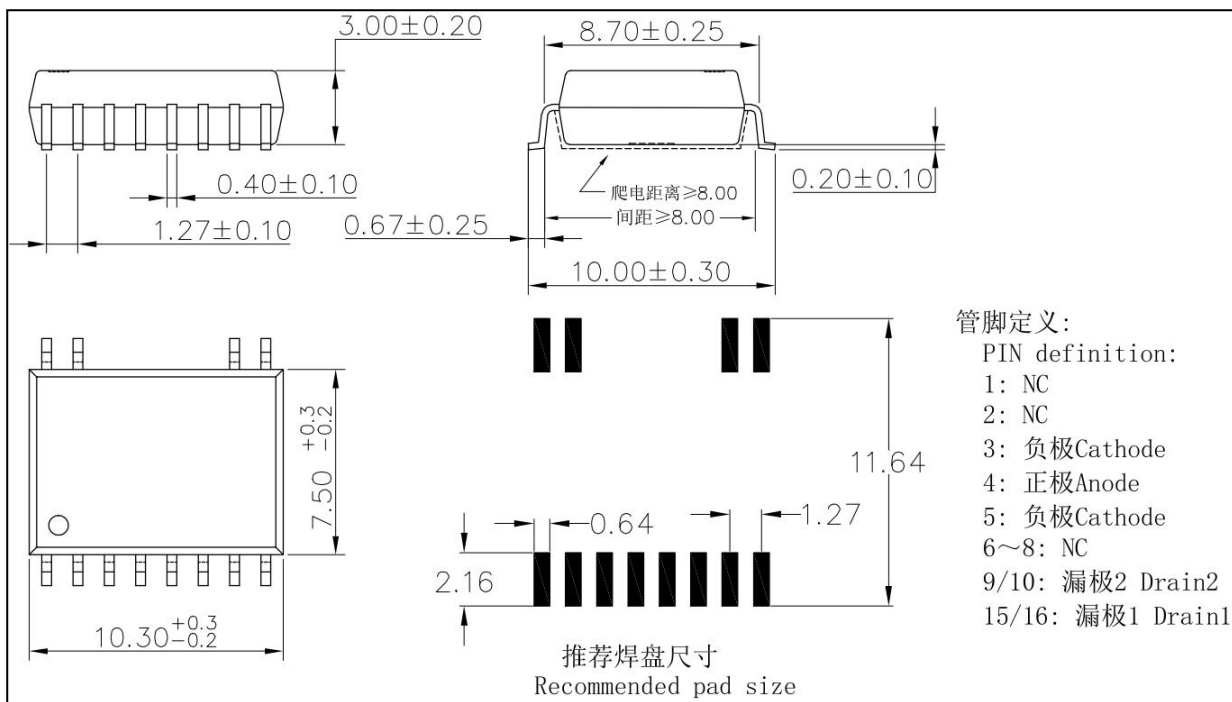


图 5 HSSR-16S1A0D-2 外形尺寸

Figure 5- The dimensions of HSSR-16S1A0D-2

9 标志 Mark

产品上应有型号、公司商标、生产日期代码、引出端识别标记。例如：HSSR-16S1A0D-2 产品印章如图 6。

Print type characters, trade mark and Lot.No. on the Photo Coupler. For example the marking of product HSSR-16S1A0D-2 is shown as figure 6.

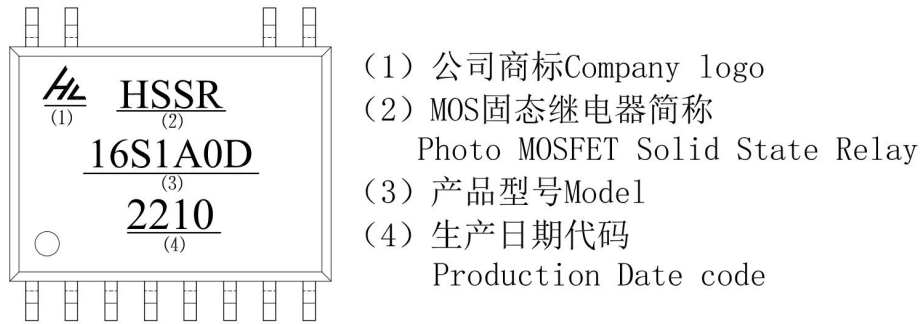


图 6 产品印章 Figure 6- Marking

10 包装方式 Packing

10.1 编带包装 (Tape and reel) : 适用于 For HSSR-16S1A0D-2。

10.1.1 每卷数量 (Qty/reel) : 1000 只 (pcs)。每箱数量 (Qty/ctn) : 10000 只 (pcs)。

10.1.2 内包装 (Inner packing) :

每卷盘 1000 只, 贴合格证 (型号、生产日期代号、检验员代号)。

1000pcs/reel, certificate on reel (model, code of product date, Inspector's code)

10.1.3 外包装(Outer packing):

公司名称、地址、商标、产品型号、数量等标志。

Indication of company name, address, trade mark, model and quantity.

10.1.4 示意图 (Schematic) :

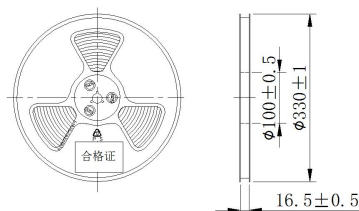
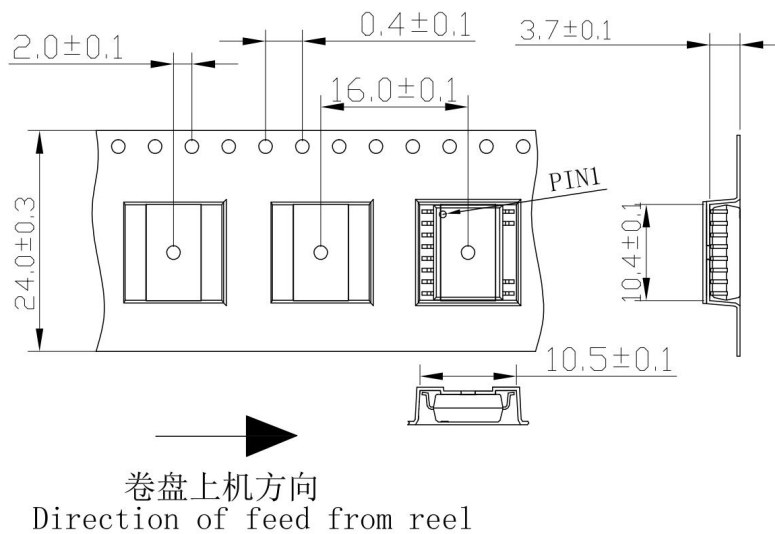


图 7 编带包装示意图

Figure 7- Taping Packing Schematic

10.2 标识 Label



图 8 标识

Figure 8-Label

11 使用注意事项 Note

11.1 推荐贮存温度 Recommend storage Temp.: 0~40°C;

推荐贮存湿度 Recommend storage humidity: <60%;

贮存有效期一年 Storage life: A year.

湿气敏感度等级 1 级。MSL level: MSL 1.

11.2 静电防护等级（人体模式） ESD(HBM): Class 2.

11.3 引脚镀锡厚度：大于等于 5μm。

Thickness of Sn which plated on lead frame: $\geq 5\mu\text{m}$.

11.4 推荐焊接条件 Recommended Soldering Conditions

11.4.1 请勿使用超过最高贮存温度的物体直接接触环氧本体。

Do not contact the epoxy body directly with objects exceeding the maximum storage temperature.

11.4.2 在高温下不要对环氧本体施加压力，特殊情况下施加的力不应超过 2.5N。

Do not apply pressure to the epoxy at high temperatures, and in special cases do not apply more than 2.5N.

11.4.3 回流焊 Reflow soldering

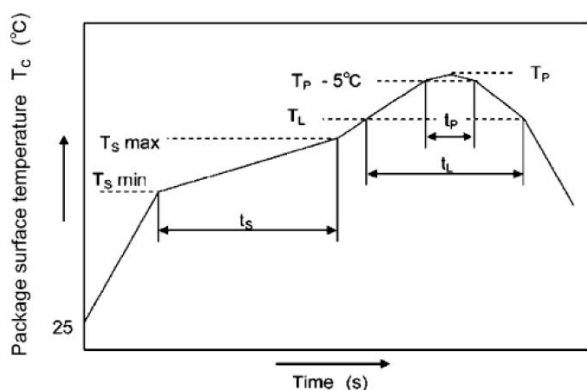
1) 推荐锡膏规格 Recommend tin glue specifications:

a) 熔点 Melting temperature: 217°C

b) 组分 Contains: SnAg3Cu0.5

2) 回流焊工序必须在器件冷却至室温后进行。Never take next process until the component is cooled down to room temperature after reflow.

3) 推荐回流焊接参数，如下图所示： The recommended reflow soldering profile is following:



	Symbol	Min	Max	Unit
Preheat temperature	T_s	150	200	°C
Preheat time	t_s	60	120	s
Ramp-up rate (T_L to T_P)			3	°C/s
Liquidus temperature	T_L	217		°C
Time above T_L	t_L	60	150	s
Peak temperature	T_P		260	°C
Time during which T_c is between ($T_P - 5$) and T_P	t_p		30	s
Ramp-down rate (T_P to T_L)			6	°C/s

图 9 回流焊参数

Figure 9-Recommended reflow soldering profile

4) 建议在所示的温度和时间条件下进行一次回流焊，最多不能超过三次。One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

11.4.4 手工烙铁焊 Manual soldering

1) 手工烙铁焊仅用于产品返修或样品测试。Manual soldering is only applicable to product repair.

2) 手工烙铁焊要求：温度 $360^{\circ}\text{C}\pm 5^{\circ}\text{C}$ ，时间 $\leq 3\text{s}$ ，返修次数 ≤ 2 次。Manual soldering requirements: temperature $\leq (360^{\circ}\text{C}\pm 5^{\circ}\text{C})$, time $\leq 3\text{s}$, repair times ≤ 2 times.

11.5 本说明书所展示的产品是为一般电子应用而设计的，如办公自动化设备、通讯设备、视听设备、电气应用和仪器仪表等。对于需要高可靠性或安全性的设备，如空间应用、核动力控制设备、医疗设备等，请与我们的销售代表联系。The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation. For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.

12 产地 Production Place

12.1 产地 Production Place: 中国厦门 Xiamen China;

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